

# N75

# Product Specifications

Issue 1.0

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Neoway Product Document



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## Notice

This document provides guide for users to use N75.

This document is intended for system engineers (SEs), development engineers, and test engineers.

THIS GUIDE PROVIDES INSTRUCTIONS FOR CUSTOMERS TO DESIGN THEIR APPLICATIONS. PLEASE FOLLOW THE RULES AND PARAMETERS IN THIS GUIDE TO DESIGN AND COMMISSION. NEOWAY WILL NOT TAKE ANY RESPONSIBILITY OF BODILY HURT OR ASSET LOSS CAUSED BY IMPROPER OPERATIONS.

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# Contents

|                                                    |           |
|----------------------------------------------------|-----------|
| <b>1 About N75 .....</b>                           | <b>1</b>  |
| 1.1 Product Overview .....                         | 1         |
| 1.2 Block Diagram .....                            | 1         |
| 1.3 Basic Features .....                           | 2         |
| <b>2 Compliant Standards .....</b>                 | <b>5</b>  |
| <b>3 Pins and Appearance .....</b>                 | <b>1</b>  |
| 3.1 Pad Layout .....                               | 1         |
| 3.2 Appearance .....                               | 2         |
| <b>4 Electric Feature and Reliability .....</b>    | <b>3</b>  |
| 4.1 Electric Features .....                        | 3         |
| 4.2 Temperature Features .....                     | 3         |
| 4.3 ESD Protection .....                           | 4         |
| <b>5 RF Features .....</b>                         | <b>5</b>  |
| 5.1 Operating Bands .....                          | 5         |
| 5.2 TX Power and RX Sensitivity .....              | 6         |
| 5.3 GNSS Feature .....                             | 6         |
| <b>6 Mechanical Features .....</b>                 | <b>8</b>  |
| 6.1 Dimensions .....                               | 8         |
| 6.2 Label .....                                    | 9         |
| 6.3 Pack .....                                     | 9         |
| 6.3.1 Reel&Tape .....                              | 9         |
| 6.3.2 Moisture .....                               | 11        |
| <b>7 Mounting N75 onto Application Board .....</b> | <b>12</b> |
| 7.1 Bottom Dimensions .....                        | 12        |
| 7.2 Application Foot Print .....                   | 13        |
| 7.3 Stencil .....                                  | 13        |
| 7.4 Solder Paste .....                             | 13        |
| 7.5 SMT Furnace Temperature Curve .....            | 14        |
| <b>8 Safety Recommendations .....</b>              | <b>15</b> |
| <b>A Conformity and Compliance .....</b>           | <b>16</b> |
| A.1 Approvals .....                                | 16        |
| A.2 American Notice .....                          | 16        |
| A.2.1 Modify .....                                 | 16        |
| A.2.2 FCC Class A Digital Device Notice .....      | 16        |
| A.2.3 FCC Class B Digital Device Notice .....      | 17        |
| <b>B Abbreviation .....</b>                        | <b>19</b> |

## Table of Figures

|                                                                |    |
|----------------------------------------------------------------|----|
| Figure 1-1 Block Diagram .....                                 | 2  |
| Figure 3-1 N75 pin definition (Top View) .....                 | 1  |
| Figure 3-1 Top view of N75 .....                               | 2  |
| Figure 3-1 Bottom view of N75.....                             | 2  |
| Figure 6-1 N75 dimensions .....                                | 8  |
| Figure 6-2 N75 label.....                                      | 9  |
| Figure 7-1 Bottom view .....                                   | 12 |
| Figure 7-2 Recommended Application Foot Print (Top View) ..... | 13 |
| Figure 7-3 SMT furnace temperature curve .....                 | 14 |

# Table of Tables

Table 1-1 Variant and frequency bands..... 1

Table 4-1 Electric features..... 3

Table 4-2 Temperature features ..... 3

Table 4-3 ESD protection features ..... 4

Table 5-1 Operating Bands ..... 5

Table 5-2 RF TX power ..... 6

# About This Document

## Scope

This document is applicable to N75series.

It defines the features, indicators, and test standards of the N75 module and provides reference for the hardware design of each interface.

Reference designs in this document are only for reference. Customers should design applications based on the actual scenarios and conditions. Please contact Neoway FAE if you have any question or doubt.

## Audience

This document is intended for system engineers (SEs), development engineers, and test engineers.

## Change History

| Issue | Date    | Change        | Changed By |
|-------|---------|---------------|------------|
| 1.0   | 2019-03 | Initial draft | WangQiang  |

## Conventions

| Symbol                                                                                         | Indication                                                                                                              |
|------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------|
| <br>Warning | This warning symbol means danger. You are in a situation that could cause fatal device damage or even bodily damage.    |
| <br>Caution | Means reader be careful. In this situation, you might perform an action that could result in module or product damages. |
| <br>Note    | Means note or tips for readers to use the module                                                                        |

## Related Documents

*Neoway\_N75\_Datasheet*

*Neoway\_N75\_Product\_Specifications*

*Neoway\_N75\_AT\_Command\_Manual*

*Neoway\_N75\_EVK\_User\_Guide*

*Neoway Module Reflow Manufacturing Recommendations*

# 1 About N75

N75 is an industrial-grade 4G module developed on Qualcomm platform. It supports GSM/GPRS/EDGE, WCDMA R99 to DC-HSPA+, and LTE Cat4. With various hardware interfaces and optional GNSS functions, N75 is well applicable to wireless metering terminals, in-vehicle terminals, POS, industrial routers, and other IoT terminals.

## 1.1 Product Overview

N75 series include multiple variants. Table 1-1 lists the variants and frequency bands supported.

Table 1-1 Variant and frequency bands

| Version | Region        | Category | Band                                                                                                          | GNSS <sup>1</sup> |
|---------|---------------|----------|---------------------------------------------------------------------------------------------------------------|-------------------|
| NA      | North America | Cat4     | FDD-LTE: B2, B4, B5, B7, B12, B13, B14, B25, B26, B66, B71<br>UMTS: B2, B4, B5<br>GSM/GPRS/EDGE: 850/1900 MHz | support           |

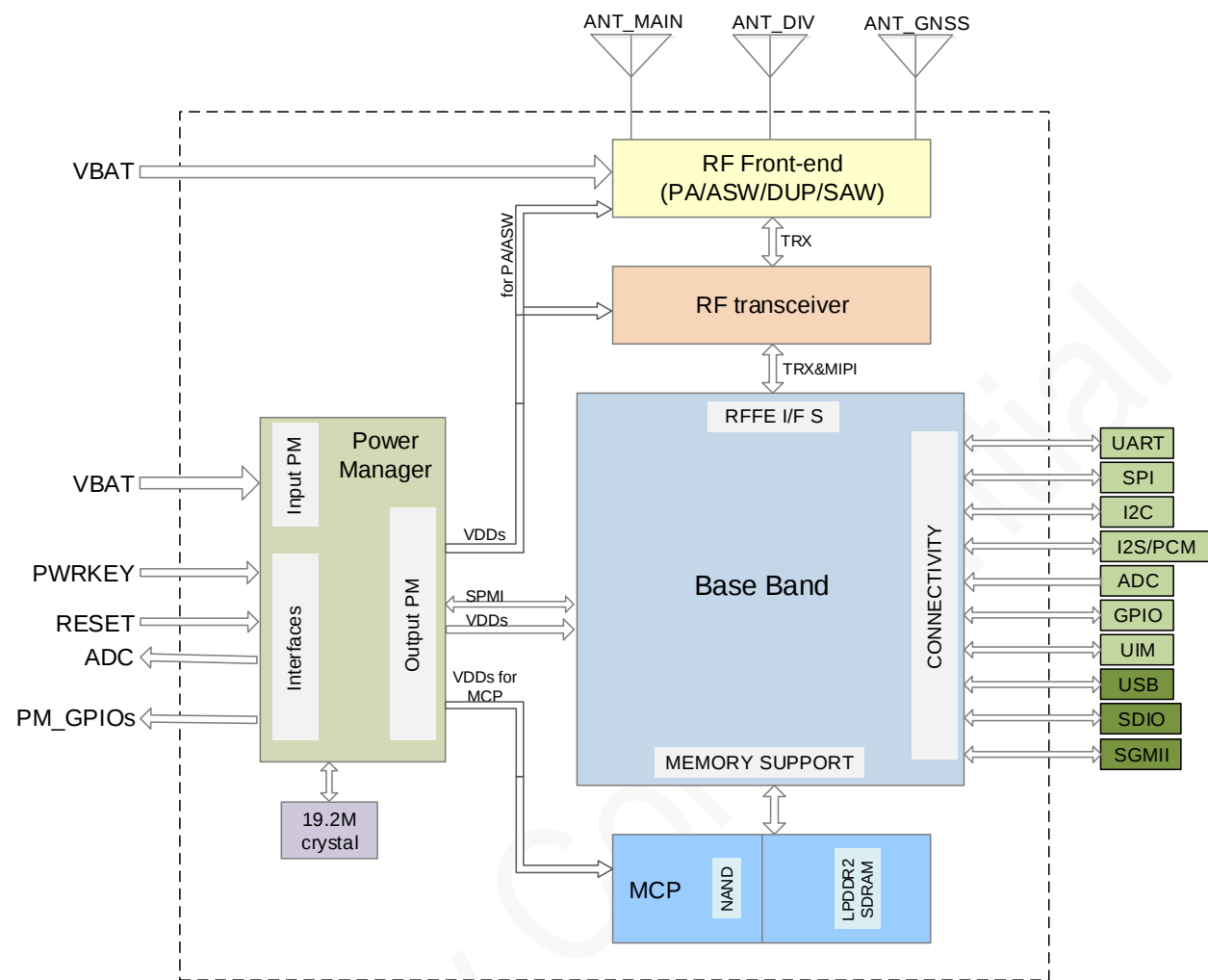
## 1.2 Block Diagram

N75 consists of the following functionality units:

- Baseband
- MCP
- Power management unit
- 19.2MHz crystal oscillator
- RF section
- Digital interfaces (UIM, SPI, I2C, SGMII, SDIO, ADC, GPIO, UART, USB)

<sup>1</sup> GNSS optional for all above variants

Figure 1-1 Block Diagram



### 1.3 Basic Features

| Parameter          | Description                        |
|--------------------|------------------------------------|
| Physical features  | Dimensions: 30 mm * 28 mm * 2.8 mm |
|                    | Weight: around 5.1g                |
| Temperature ranges | Operating: -35°C to +75°C          |
|                    | Extended: -40°C to +85°C           |
|                    | Storage: -45°C to +90°C            |
| Operating voltage  | VBAT: 3.3V to 4.3V, TYP: 3.8V      |

|                        |                                                                                                                      |
|------------------------|----------------------------------------------------------------------------------------------------------------------|
| Operating Current      | Sleep <sup>2</sup> : < 4 mA                                                                                          |
|                        | Idle <sup>3</sup> : < 20 mA                                                                                          |
|                        | Operating mode <sup>4</sup> (LTE networks)                                                                           |
|                        | Current in data service: about 250 mA<br>Current in max. RX power: about 580 mA (FDD-LTE B1), 380mA (TDD-LTE Band41) |
| MIPS processor         | ARM Cortex-A7 processor, 1.3 GHz main frequency                                                                      |
| Memory                 | ROM+RAM: 2Gb+1Gb                                                                                                     |
| Operating Bands        | See Table 1-1.                                                                                                       |
| Wireless rate          | GPRS: Max 85.6 Kbps(DL) / Max 85.6 Kbps(UL)                                                                          |
|                        | EDGE: Max 236.8Kbps(DL) / Max 236.8Kbps(UL)                                                                          |
|                        | WCDMA: DC-HSPA+, Max 42Mbps (DL)/Max 5.76Mbps (UL)                                                                   |
|                        | FDD-LTE: non-CA cat4, Max 150 Mbps(DL)/Max 50 Mbps (UL)                                                              |
| Transmit power         | GSM850: +33dBm (Power Class 4)                                                                                       |
|                        | PCS1900: +30dBm (Power Class 1)                                                                                      |
|                        | EDGE 850MHz: +27dBm (Power Class E2)                                                                                 |
|                        | EDGE1900MHz: +26dBm (Power Class E2)                                                                                 |
|                        | UMTS: +23dBm (Power Class 3)                                                                                         |
|                        | LTE: +23dBm (Power Class 3)                                                                                          |
| Application Interfaces | 2G/3G/4G antenna, diversity antenna, GNSS antenna<br>50Ω impedance                                                   |
|                        | Two UART interfaces: one is an ordinary serial port, and one is used for Bluetooth by default                        |
|                        | One I2C interface, supporting only host mode                                                                         |
|                        | One SPI interface, supporting only host mode and max. 50 Mbp                                                         |
|                        | One USIM interface, 1.8V/2.85V                                                                                       |
|                        | One USB2.0 interface, OTG function requires external 5V DC-DC                                                        |
|                        |                                                                                                                      |

<sup>2</sup> Sleep mode is the low power consumption state the module enters. In this mode, peripheral interfaces of the module are disabled but the RF function works. If a call or SMS message incomes, the module exits from sleep mode. After the call or voice is end, the module enters sleep mode again.

<sup>3</sup> Idle mode indicates the status of no service when the module is running.

<sup>4</sup> Current in operating mode indicates the current during data communication. For currents of other network modes and bands, see N75 Current Test Report.

|                        |                                                                        |
|------------------------|------------------------------------------------------------------------|
|                        | Two 15-bit ADC interfaces, detectable voltage ranging from 0.1 to 1.7V |
|                        | One I2S/PCM interface, used to connect to CODEC chipset                |
|                        | One SDIO interface, used to control WLAN                               |
|                        | One SGMII/MDIO interface, used for Ethernet                            |
|                        | Four GPIO interfaces                                                   |
| AT Command             | Neoway extended commands                                               |
| Data                   | PPP, RNDIS, ECM, RMNET                                                 |
| Protocol               | TCP, UDP, MQTT, FTP/FTPS, HTTP/HTTP(S), SSL, TLS                       |
| Certification approval | FCC, PTCRB, AT&T, CE-R, GCF, RoHS, NCC*, RCM*                          |

## 2 Compliant Standards

- 3GPP TS 07.07AT command set for GSM Mobile Equipment (ME)
- YD 1214-2006 Technical requirement of 900/1800MHz TDMA Digital Cellular Mobile Telecommunication Network General Packet Radio Service (GPRS)Equipment: Mobile Stations
- YD 1215-2006Testing Methods of 900/1800MHz TDMA Digital Cellular Mobile Telecommunication Network General Packet Radio Service (GPRS)Equipment: Mobile Stations
- YD 1032-2000Limits and Measurement Methods of Electromagnetic Compatibility for 900/1800MHz Digital Cellular Telecommunications System Part1:Mobile Station and Ancillary Equipment
- YD/T 2220-2011 Technical Requirement and test method of WCDMA/GSM(GPRS) dual mode digit mobile user equipment (phase 4)
- Ministry of Industry and Information Technology PRC, Measures for the Network Access Management of Telecommunication Equipment (2014 Amendment)
- GB4943.1-2011 Information technology equipment - Safety - Part 1: General requirements
- GB/T22450.1-2008 Limits and measurement methods of electromagnetic compatibility for 900/1800MHz TDMA digital cellular telecommunications system - Part 1: Mobile station and ancillary equipment
- CNCA-O7C-031:2007Rules for Compulsory Certification of Telecommunication Equipment Telecommunication Terminal Equipment
- 3GPP TS GSM Specification Set
- 3GPP TS WCDMA Specification Set
- 3GPP TS LTE Cat4 4GSpecification Set

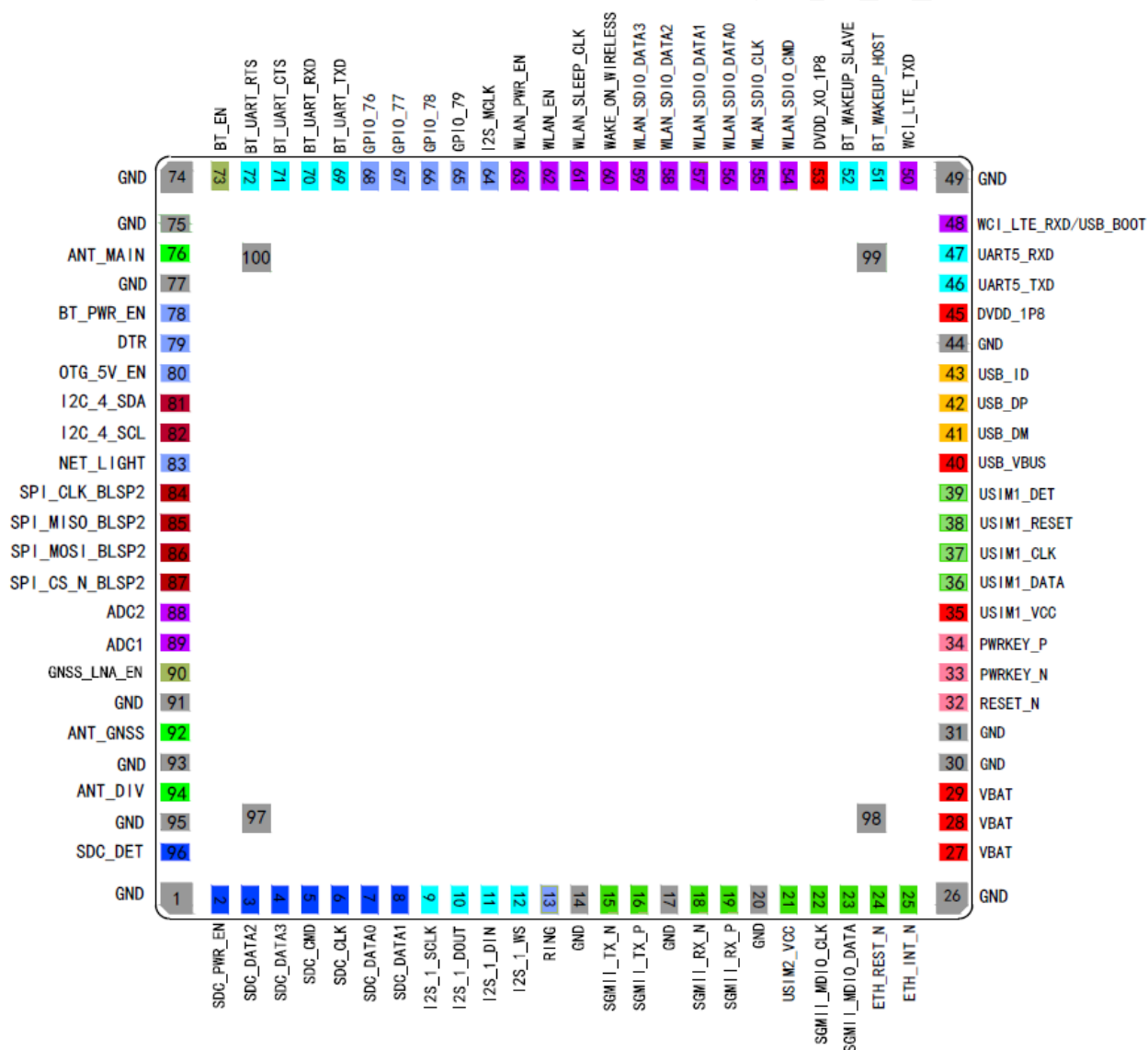
## 3 Pins and Appearance

There are 100 pins on N75 and their pads are introduced in LGA package.

### 3.1 Pad Layout

Figure 2-1 shows the pad layout of N75.

Figure 3-1 N75 pin definition (Top View)

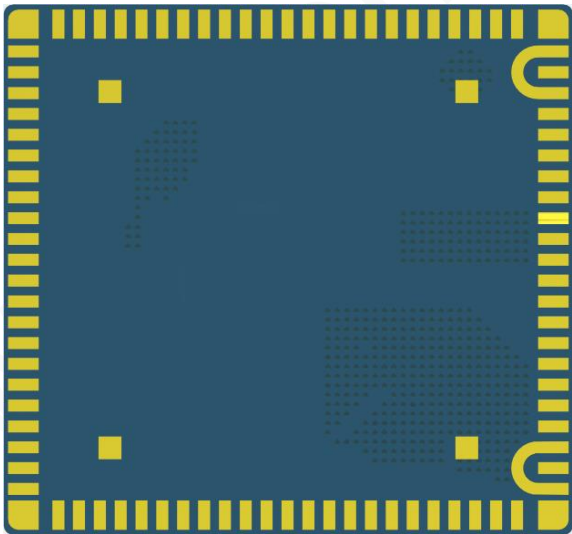


3.2 Appearance

Figure 3-1 Top view of N75



Figure 3-1 Bottom view of N75



Note

Label in the above figure indicates N75 NA variant. Labels of other variants are similar.

## 4 Electric Feature and Reliability

This chapter describes the electric features and reliability of N75, including current and voltage of each power pin, operating and storage temperature ranges, and ESD protection features.

### 4.1 Electric Features

Table 4-1 Electric features

| Parameter |                 | Minimum Value | Typical Value | Maximum Value |
|-----------|-----------------|---------------|---------------|---------------|
| VBAT      | V <sub>in</sub> | 3.3V          | 3.8V          | 4.3V          |
|           | I <sub>in</sub> | /             | /             | 2A            |



Caution

- If the voltage is lower than threshold, the module might fail to start. If the voltage is higher than threshold or there is a voltage burst during the startup, the module might be damaged permanently.
- If you use LDO or DC-DC to supply power for the module, ensure that it outputs at least 2 A current. When the module works at maximum power in GSM mode, the peak current might reach 2A. Add a large capacitor to the VBAT pin to enhance the capability to output continuous current and avoid voltage drop.

### 4.2 Temperature Features

Table 4-2 Temperature features

| Status              | Minimum Value | Typical Value | Maximum Value |
|---------------------|---------------|---------------|---------------|
| Operating           | -35℃          | 25℃           | 75℃           |
| Extended            | -40℃          |               | 85℃           |
| Storage temperature | -45℃          |               | 90℃           |



Note

If the module works in an environment of -35℃ to -40℃ or 75℃ to 85℃, RF performance might be worse. This does not affect the running of the module. The RF performance will meet the 3GPP standard after the temperature reaches the operating range.

## 4.3 ESD Protection

Electronics need to pass ESD tests. Table 4-3 shows the ESD capability of key pins of this module. It is recommended to add ESD protection based on the application scenarios to ensure product quality when designing a product.

Humidity 45%    Temperature 25°C

Table 4-3 ESD protection features

| Testing Point | Contact Discharge | Air Discharge |
|---------------|-------------------|---------------|
| VBAT          | ±8kV              | ±15kV         |
| GND           | ±8kV              | ±15kV         |
| ANT           | ±8kV              | ±15kV         |
| Cover         | ±8kV              | ±15kV         |
| Others        | ±2kV              | ±4kV          |

## 5 RF Features

N75 supports 2G/3G/4G network modes and frequency bands as well as GNSS function. This chapter describes the RF features of N75.

### 5.1 Operating Bands

Table 5-1 Operating Bands

| Operating Bands | Uplink       | Downlink     |
|-----------------|--------------|--------------|
| GSM850          | 824~849MHz   | 869~894MHz   |
| PCS1900         | 1850~1910MHz | 1930~1990MHz |
| UMTS B2         | 1850~1910MHz | 1930~1990MHz |
| UMTS B4         | 1710~1755MHz | 2110~2155MHz |
| UMTS B5         | 824~849MHz   | 869~894MHz   |
| FDD-LTE B2      | 1850~1910MHz | 1930~1990MHz |
| FDD-LTE B4      | 1710~1755MHz | 2110~2155MHz |
| FDD-LTE B5      | 824~849MHz   | 869~894MHz   |
| FDD-LTE B7      | 2500~2570MHz | 2620~2690MHz |
| FDD-LTE B12     | 699~716MHz   | 728~746MHz   |
| FDD-LTE B13     | 777~787MHz   | 746~757MHz   |
| FDD-LTE B14     | 788~798MHz   | 758~768MHz   |
| FDD-LTE B25     | 1850~1915MHz | 1930~1995MHz |
| FDD-LTE B26     | 814~849MHz   | 859~894MHz   |
| TDD-LTE B66     | 1710~1780MHz | 2110~2200MHz |
| TDD-LTE B71     | 617~652MHz   | 663~698MHz   |

## 5.2 TX Power and RX Sensitivity

Table 5-2 RF TX power

| Band        | TX Power       | RX Sensitivity |
|-------------|----------------|----------------|
| GSM850      | 33dBm+2/-2dBm  | <-110dBm       |
| PCS1900     | 30dBm+2/-2dBm  | <-110dBm       |
| UMTS B2     | 24dBm +1/-3dBm | <-110dBm       |
| UMTS B4     | 24dBm +1/-3dBm | <-110dBm       |
| UMTS B5     | 24dBm +1/-3dBm | <-110dBm       |
| FDD-LTE B2  | 23dBm+2/-2dBm  | <-98dBm        |
| FDD-LTE B4  | 23dBm+2/-2dBm  | <-98dBm        |
| FDD-LTE B5  | 23dBm+2/-2dBm  | <-98dBm        |
| FDD-LTE B7  | 23dBm+2/-2dBm  | <-96dBm        |
| FDD-LTE B12 | 23dBm+2/-2dBm  | <-95dBm        |
| FDD-LTE B13 | 23dBm+2/-2dBm  | <-95dBm        |
| FDD-LTE B14 | 23dBm+2/-2dBm  | <-95dBm        |
| FDD-LTE B25 | 23dBm+2/-2dBm  | <-98dBm        |
| FDD-LTE B26 | 23dBm+2/-2dBm  | <-98dBm        |
| TDD-LTE B66 | 23dBm+2/-2dBm  | <-98dBm        |
| TDD-LTE B71 | 23dBm+2/-2dBm  | <-95dBm        |



Note

All values above were obtained in the lab. In actual applications, there might be a difference because of network environments.

## 5.3 GNSS Feature

| Changes                     | Parameter         |
|-----------------------------|-------------------|
| GPS L1 operating frequency  | 1575.42±1.023MHz  |
| GLONASS operating frequency | 1597.5~1605.9 MHz |
| BDS operation frequency     | 1559.1~1563.1 MHz |

|                                |                                              |
|--------------------------------|----------------------------------------------|
| Tracking sensitivity           | -160dBm (GPS)/-159.5 dBm (GLONASS)/TBD (BDS) |
| Acquisition sensitivity        | -144dBm (GPS)/-143.5 dBm (GLONASS)           |
| Positioning precision (in air) | < 3m (CEP50)                                 |
| Hot start (in air)             | <2.5s                                        |
| Cold start (in air)            | <35s                                         |
| Update frequency               | 1Hz by default                               |
| CNRin/CNRout                   | 3dB                                          |
| Max. positioning altitude      | 18000m                                       |
| Max. positioning speed         | 515m/s                                       |
| Max. positioning acceleration  | 4g                                           |
| GNSS data type                 | NMEA-0183                                    |
| GNSS antenna type              | Passive/active antenna                       |



Note

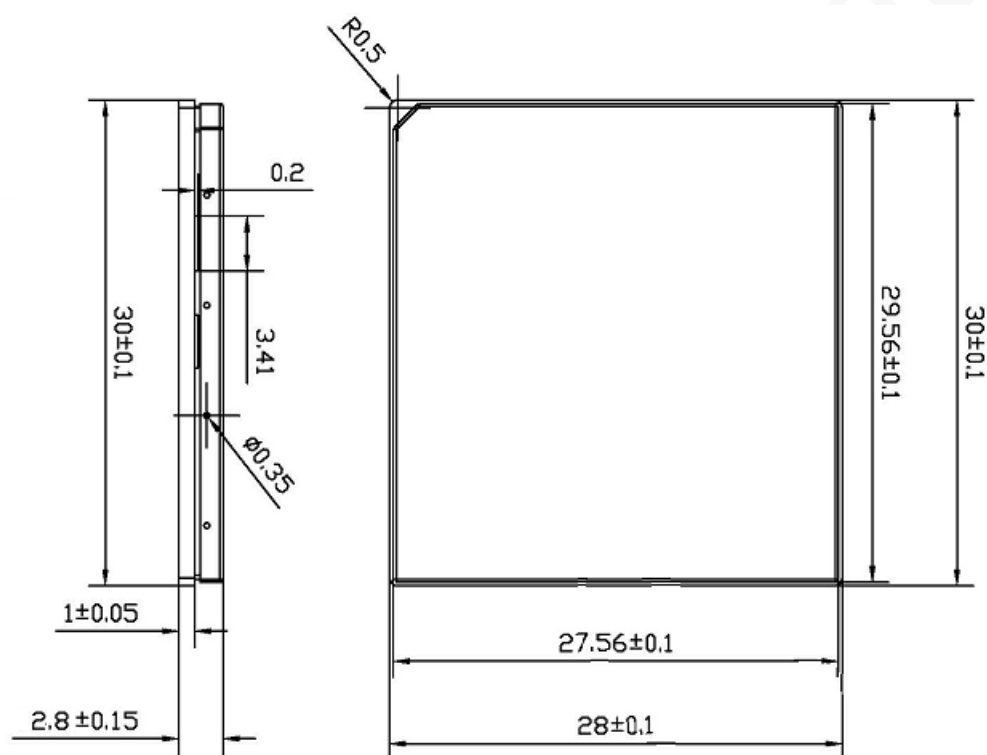
Tracking sensitivity, acquisition sensitivity, and re-acquisition sensitivity were obtained in signaling test on SPIRENT6300 and they are the maximum values of multiple tests on samples.No external LNA or active antenna was used in the test.

## 6 Mechanical Features

This chapter describes the mechanical features of N75.

### 6.1 Dimensions

Figure 6-1 N75 dimensions



The unit is mm.

## 6.2 Label

The label is made of materials that are deformation-resistant, fade-resistant, and high-temperature-resistant and it can endure high temperature up to 260 °C.

Figure 6-2 N75 label



Note

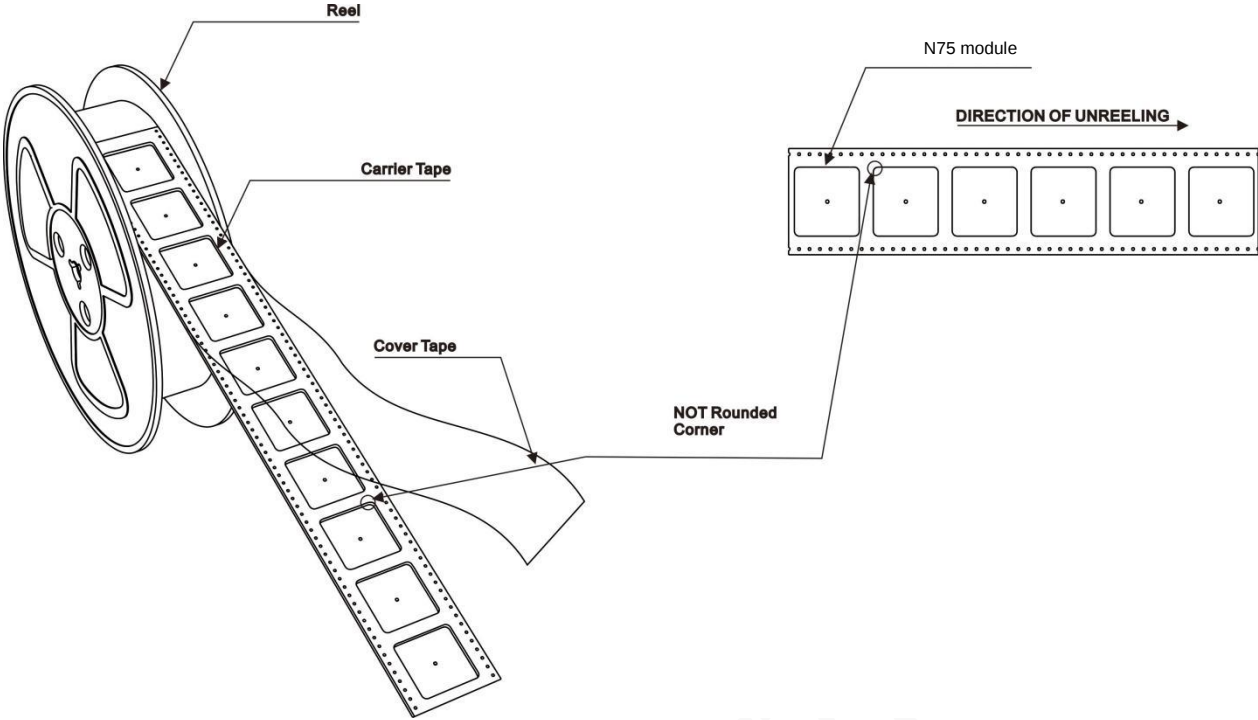
- The picture above is only for reference.
- The silk-screen printing must be clear. No blur is allowed.
- The material and surface finishing must comply with RoHS directives.

## 6.3 Pack

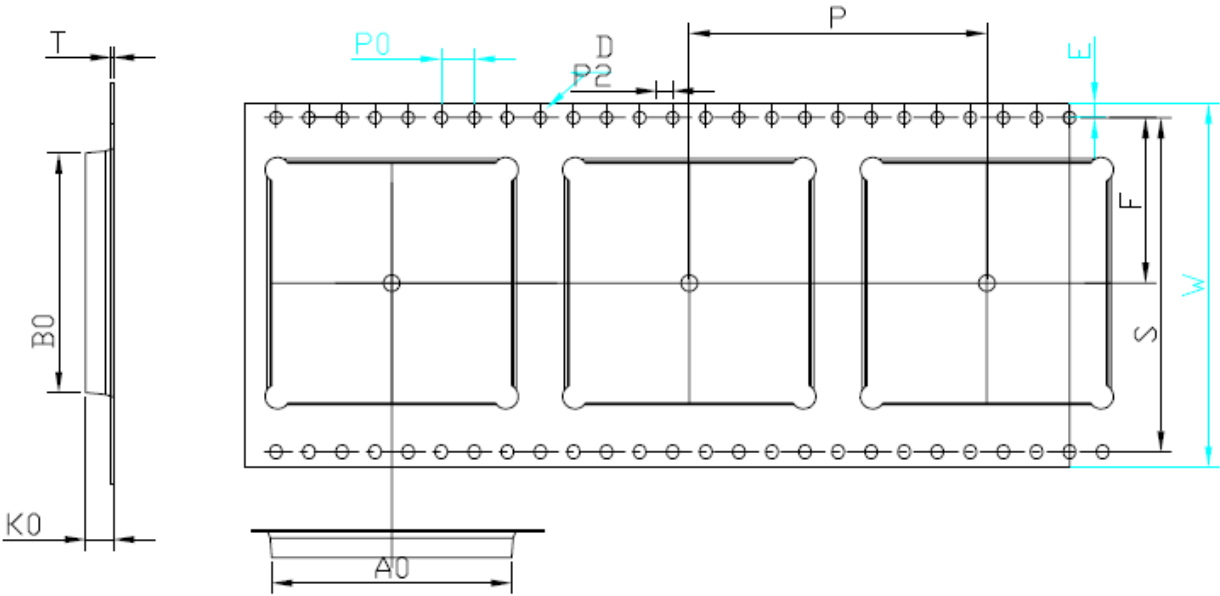
N75 modules are packaged in sealed vacuum bags with dryer, humidity card, and tray on delivery to guarantee a long shelf life. Follow the same package method again in case of opened for any reasons.

### 6.3.1 Reel&Tape

N75 in mass production are shipped in the following package.

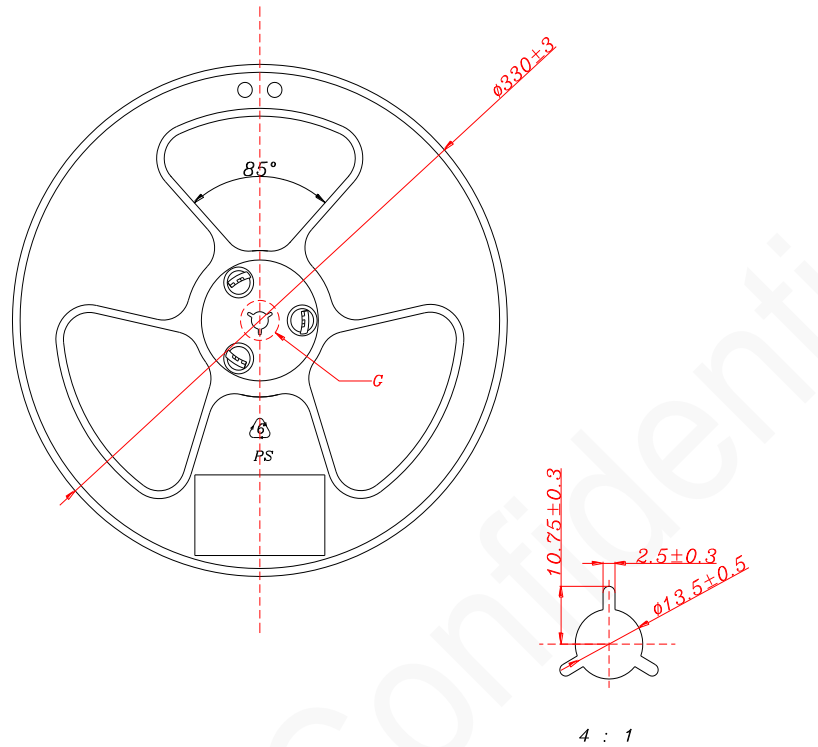


Tape



| ITEM | W            | A0           | B0           | S            | D            | E    | F     | K0           | P0   | P2   | P    | T     |
|------|--------------|--------------|--------------|--------------|--------------|------|-------|--------------|------|------|------|-------|
| DIM  | 44.0         | 28.7         | 28.70        | 40.4         | 1.5          | 1.75 | 20.2  | 3.55         | 4.0  | 2.0  | 36.0 | 0.30  |
| TOLE | +0.3<br>-0.3 | +0.1<br>-0.1 | +0.1<br>-0.1 | +0.1<br>-0.0 | +0.1<br>-0.0 | ±0.1 | ±0.10 | +0.1<br>-0.1 | ±0.1 | ±0.1 | ±0.1 | ±0.05 |

## Reel



### 6.3.2 Moisture

N75 is a level 3 moisture-sensitive electronic elements, in compliance with IPC/JEDEC J-STD-020 standard.

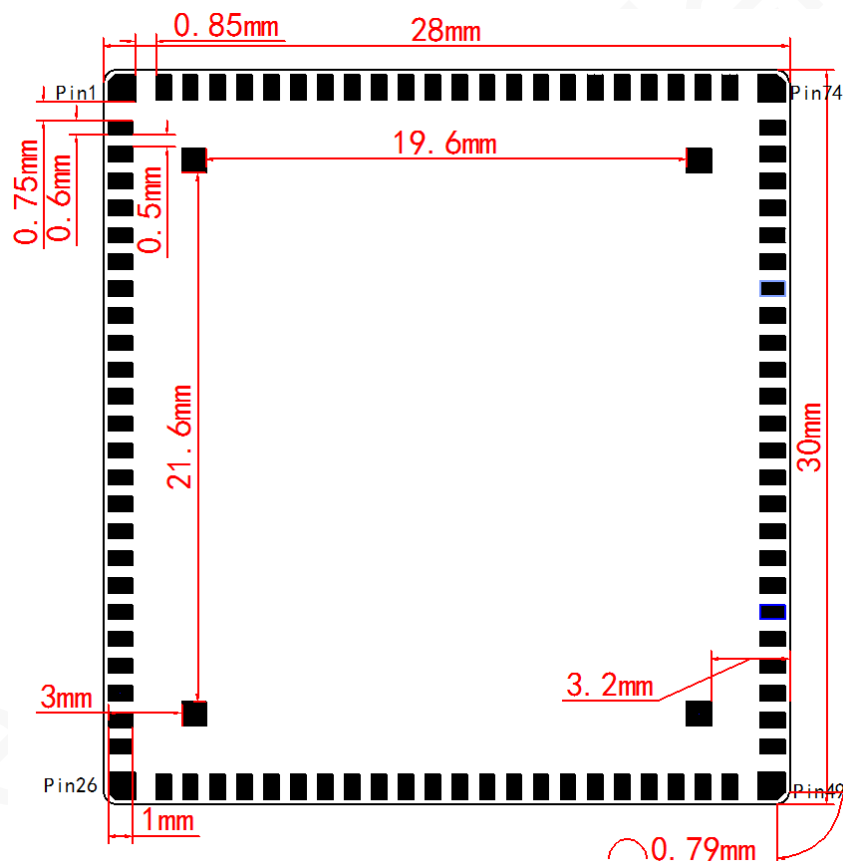
If the module is exposed to air for more than 48 hours at conditions not worse than 30°C/60% RH, bake it at a temperature higher than 90 degree for more than 12 hours before SMT.Or, if the indication card shows humidity greater than 20%, the baking procedure is also required.Do not bake modules with the package tray directly.

## 7 Mounting N75 onto Application Board

N75 is introduced in 100-pin LGA package. This chapter describes N75V5 foot print, recommended PCB design and SMT information to guide users how to mount the module onto application PCB board.

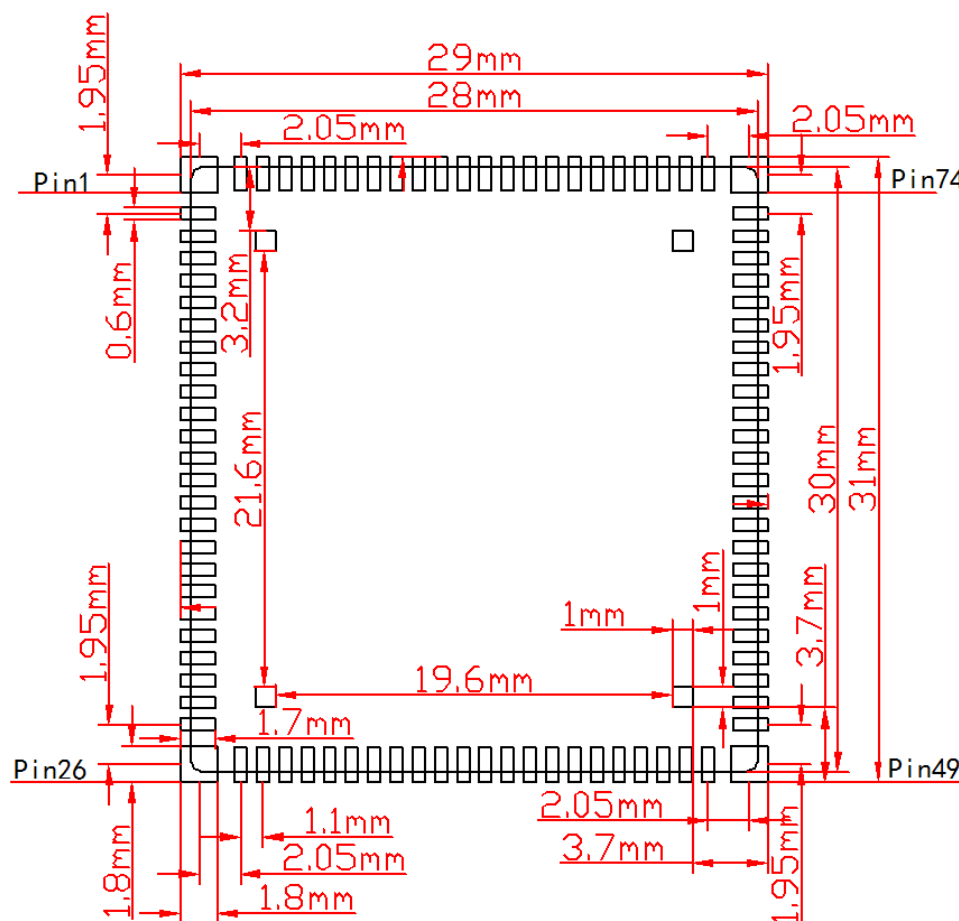
### 7.1 Bottom Dimensions

Figure 7-1 Bottom view



## 7.2 Application Foot Print

Figure 7-2 Recommended Application Foot Print (Top View)



## 7.3 Stencil

The recommended stencil thickness is at least 0.12 mm to 0.15 mm.

## 7.4 Solder Paste

The quality of the solder joint depends on the solder paste volume and the PCB flatness.

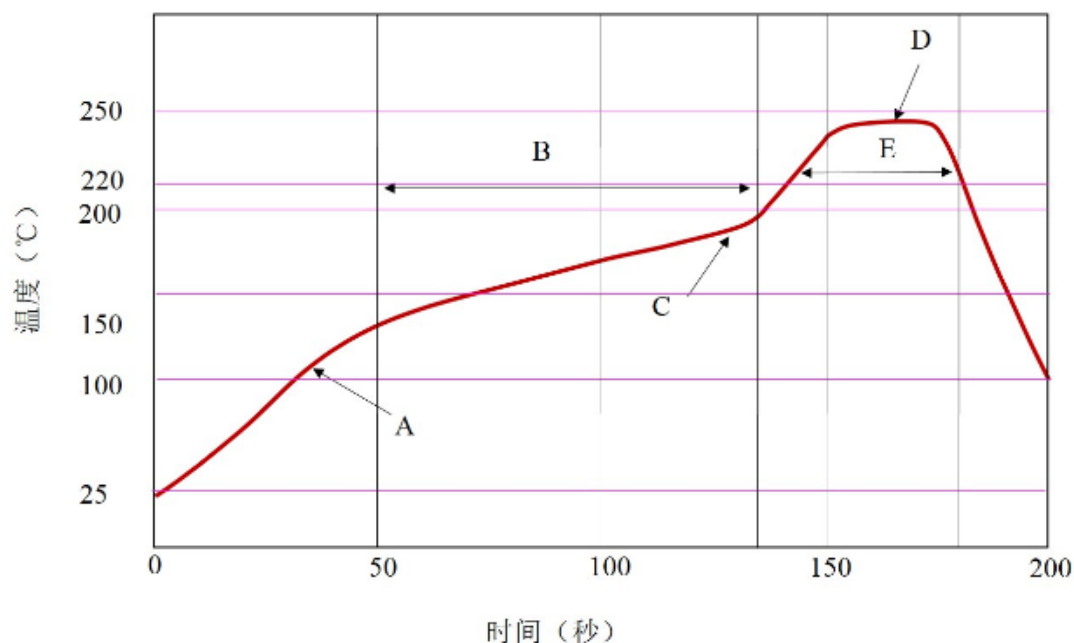
Do not use the kind of solder paste different from our module technique.

- The melting temperature of solder paste with lead is 35 °C lower than that of solder paste without lead. It is easy to cause voiding for LGA and LCC inside the module after second reflow soldering.
- When using only solder pastes with lead, please ensure that the reflow temperature is kept at 220 °C for more than 45 seconds and the peak temperature reaches 240 °C.

## 7.5 SMT Furnace Temperature Curve

Thin or long PCB might bend during SMT. So, use loading tools during the SMT and reflow soldering process to avoid poor solder joint caused by PCB bending.

Figure 7-3 SMT furnace temperature curve



Technical parameters:

- Ramp up rate: 1 to 4 °C/sec
- Ramp down rate: -3 to -1 °C/sec
- Soaking zone: 150-180 °C, Time: 60-100 s
- Reflow zone: >220 °C, Time: 40-90 s
- Peak temperature: 235-250 °C



Warning

Neoway will not provide warranty for heat-responsive element abnormalities caused by improper temperature control.

For information about cautions in N75 storage and mounting, refer to *Neoway Module Reflow Manufacturing Recommendations*.

When manually desoldering the module, use heat guns with great opening, adjust the temperature to 250 degrees (depending on the type of the solder paste), and heat the module till the solder paste is melt. Then remove the module using tweezers. Do not shake the module in high temperatures while removing it. Otherwise, the components inside the module might get misplaced.

## 8 Safety Recommendations

Ensure that this product is used in compliant with the requirements of the country and the environment. Please read the following safety recommendations to avoid body hurts or damages of product or work place:

- Do not use this product at any places with a risk of fire or explosion such as gasoline stations, oil refineries, etc
- Do not use this product in environments such as hospital or airplane where it might interfere with other electronic equipment.

Please follow the requirements below in application design:

- Do not disassemble the module without permission from Neoway. Otherwise, we are entitled to refuse to provide further warranty.
- Please design your application correctly by referring to the HW design guide document and our review feedback on your PCB design. Please connect the product to a stable power supply and lay out traces following fire safety standards.
- Please avoid touch the pins of the module directly in case of damages caused by ESD.
- Do not remove the USIM card in idle mode if the module does not support hot plugging.

# A Conformity and Compliance

## A.1 Approvals

- FCC
- PTCRB
- AT&T
- CE-R
- GCF
- RoHS
- NCC\*
- RCM\*

## A.2 American Notice

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions:

- (1) This device may not cause harmful interference, and
- (2) this device must accept any interference received, including interference that may cause undesired operation.

### A.2.1 Modify

Changes or modifications made to this equipment, not expressly approved by us or parties authorized by us could void the user's authority to operate the equipment.

### A.2.2 FCC Class A Digital Device Notice

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a commercial environment. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

## A.2.3 FCC Class B Digital Device Notice

### FCC Regulations:

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) This device must accept any interference received, including interference that may cause undesired operation.

Caution: Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

### RF Exposure Information

This device complies with FCC radiation exposure limits set forth for an uncontrolled environment. In order to avoid the possibility of exceeding the FCC radio frequency exposure limits, human proximity to the antenna shall not be less than 20cm (8 inches) during normal operation.

### IMPORTANT NOTE:

This module is intended for OEM integrator. The OEM integrator is still responsible for the FCC compliance requirement of the end product, which integrates this module. 20cm minimum distance has to be able to be maintained between the antenna and the users for the host this module is integrated into. Under such configuration, the FCC radiation exposure limits set forth for an uncontrolled environment can be satisfied.

Any changes or modifications not expressly approved by the manufacturer could void the user's authority to operate this equipment.

### USERS MANUAL OF THE END PRODUCT:

In the users manual of the end product, the end user has to be informed to keep at least 20cm separation with the antenna while this end product is installed and operated. The end user has to be informed that the FCC radio-frequency exposure guidelines for an uncontrolled environment can be satisfied. The end user has to also be informed that any changes or modifications not expressly approved by the manufacturer could void the user's authority to operate this equipment. If the size of the end product is smaller than 8x10cm, then additional FCC part 15.19 statement is required to be available in the users manual: This device complies with Part 15 of FCC rules. Operation is subject to the following two conditions: (1) this device may not cause harmful interference and (2) this device must accept any interference received, including interference that may cause undesired operation.

### LABEL OF THE END PRODUCT:

The final end product must be labeled in a visible area with the following "Contains Transmitter Module **FCC ID: PJ7-N75-NA**". If the size of the end product is larger than 8x10cm, then the following FCC part 15.19 statement has to also be available on the label: This device complies with Part 15 of FCC rules.

Operation is subject to the following two conditions: (1) this device may not cause harmful interference and (2) this device must accept any interference received, including interference that may cause undesired operation.

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## B Abbreviation

| Abbreviation | English Full Name                                       |
|--------------|---------------------------------------------------------|
| ADC          | Analog-Digital Converter                                |
| bps          | Bits per second                                         |
| BLSP         | BAM low-speed peripheral                                |
| DC-HSPA+     | Dual-carrier HSPA+                                      |
| EDGE         | Enhanced GSM                                            |
| EV-DO        | Evolution Data Optimized                                |
| FDD          | Frequency Division Duplex                               |
| GNSS         | Global Navigation Satellite System                      |
| GPIO         | General-Purpose Input/Output                            |
| GPRS         | General Packet Radio Service                            |
| HSPA+        | High-Speed Packet Access                                |
| I2C          | Interintegrated Circuit                                 |
| I2S          | Inter-IC Sound                                          |
| LGA          | Land Grid Array                                         |
| LTE          | Long-Term Evolution                                     |
| MDIO         | Management Data Input/Output                            |
| PCB          | Printed Circuit Board                                   |
| PCM          | Pulse-Coded Modulation                                  |
| PM           | Power management unit                                   |
| RF           | Radio Frequency                                         |
| SDC          | Secure Digital Controller                               |
| SGMII        | Serial Gigabit Media Independent Interface              |
| SPI          | Serial Peripheral Interface                             |
| TD-SCDMA     | Time Division-Synchronous Code Division Multiple Access |

|         |                                             |
|---------|---------------------------------------------|
| UART    | Universal asynchronous receiver-transmitter |
| USIM    | Universal Subscriber Identity Module        |
| UMTS    | Universal Mobile Telecommunications System  |
| USB     | Universal Serial Bus                        |
| USB-OTG | Universal serial bus on-the-go              |
| WCDMA   | Wide-band Code Division Multiple Access     |
| WCI     | Wireless Coexistence Interface              |
| WLAN    | Wireless Local Area Network                 |